	grated Device Technolog Silver Creek Valley Ro		5138			
PRODUCT/PROCESS CHANGE NOTICE (PCN)						
PCN #: F1712-01 I Product Affected: FCBGA-400 (RoHS5) (80HCPS1616CHR , 8		MEANS OF DISTI Product Mark Back Mark Date Code Other	NGUISHING CHANGED DEVICES: Change in the top mark and orderable part#			
Date Effective: 12-Apr-2018						
Contact: IDT PCN DESK E-mail: <u>pcndesk@idt.com</u>		Attachment: Samples: Please co sample re	Yes No ntact your local sales representative for equest & availability.			
DESCRIPTION AND PURPOSE OF CHANGE: Die Technology Wafer Fabrication Process Assembly Process Equipment Material Testing Data Sheet Other						
RELIABILITY/QUALIFICATION SUM Refer to qualification data shown in attachme						
CUSTOMER ACKNOWLEDGMENT OF IDT records indicate that you require written to grant approval or request additional inform it will be assumed that this change is accepta IDT reserves the right to ship either version is on the earlier version has been depleted.	n notification of this char nation. If IDT does not n able.	receive acknowledge	ment within 30 days of this notice			
Customer:	C] Approval for	shipments prior to effective date.			
Name/Date:	Name/Date: E		Mail Address:			
Title: Phone# /Fax# :						
CUSTOMER COMMENTS:						
IDT ACKNOWLEDGMENT OF RECEIN RECD. BY:		DATE:				



Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : F1712-01

PCN Type:	Material Change from RoHS 5 to Green		
Data Sheet Change:	None		
	No change in moisture sensitivity level (MSL)		

Detail Of Change:

This notification is to advise our customers that IDT is converting from RoHS5 to Green package materials to meet industry materials requirements.

The material set details of the current and replacement part is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Replacement Parts

	Current Part (RoHS5)Replacement F (Green)	
Assembly Location	Amkor Taiwan ASE Taiwan	ASE Taiwan
Die bump	63Sn37Pb	Sn1.8Ag
Solder balls	Sn96.5/Ag3.0/Cu0.5	Sn96.5/Ag3.0/Cu0.5

Affected Part List

Current Part# (RoHS5)	Replacement Part# (Green)		
80HCPS1616CHR	80HCPS1616CHLG		
80HCPS1616CHRI	80HCPS1616CHLGI		



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : F1712-01

Qualification Information and Qualification Data:

Affected Packages:	FCBGA-400
Assembly Material:	Shown on page 2 of this attachment.
Qual Plan & Results:	Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: FCBGA-784

Test Description	Test Method	Test Results (Rej / SS)		
Test Description	Test Method	Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - Unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Solder Ball Shear Test	JESD22-B117	0/5	0/5	0/5
X Ray	IDT Spec. MAC- 3012	0/45	0/45	0/45
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 4, 245 °C	0/25	0/25	0/25

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*Note: Tests were subjected to Preconditioning per JESD22-A113 prior to stress test